

Welcome to [E-XFL.COM](#)

**[Embedded - Microcontrollers - Application Specific](#): Tailored Solutions for Precision and Performance**

**[Embedded - Microcontrollers - Application Specific](#)**

represents a category of microcontrollers designed with unique features and capabilities tailored to specific application needs. Unlike general-purpose microcontrollers, application-specific microcontrollers are optimized for particular tasks, offering enhanced performance, efficiency, and functionality to meet the demands of specialized applications.

**[What Are Embedded - Microcontrollers - Application Specific?](#)**

Application-specific microcontrollers are engineered to

**Details**

Product Status	Active
Applications	USB Type C
Core Processor	ARM® Cortex®-M0
Program Memory Type	FLASH (32KB)
Controller Series	-
RAM Size	4K x 8
Interface	I²C, SPI, UART/USART, USB
Number of I/O	14
Voltage - Supply	1.71V ~ 5.5V
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	24-UFQFN Exposed Pad
Supplier Device Package	24-QFN (4x4)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/infineon-technologies/cypd2134-24lqxi">https://www.e-xfl.com/product-detail/infineon-technologies/cypd2134-24lqxi</a>

## Available Firmware and Software Tools

### EZ-PD Configuration Utility

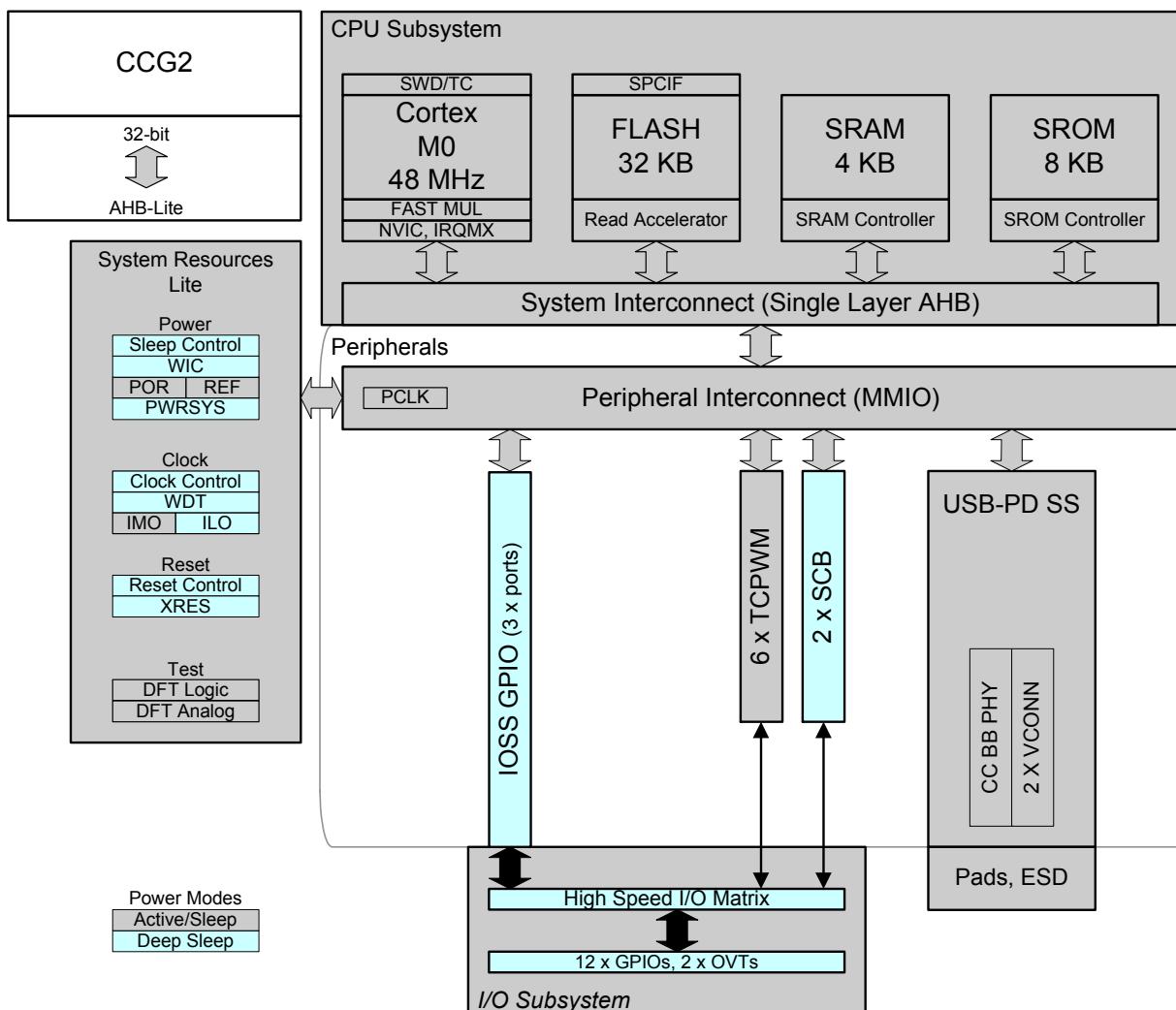
The EZ-PD Configuration Utility is a GUI-based Microsoft Windows application developed by Cypress to guide a CCGx user through the process of configuring and programming the chip. The utility allows users to:

1. Select and configure the parameters they want to modify
2. Program the resulting configuration onto the target CCGx device.

The utility works with the Cypress supplied CCG1, CCG2, CCG3, and CCG4 kits, which host the CCGx controllers along with a USB interface. This version of the EZ-PD Configuration Utility supports configuration and firmware update operations on CCGx controllers implementing EMCA and Display Dongle applications. Support for other applications, such as Power Adapters and Notebook port controllers, will be provided in later versions of the utility.

You can download the EZ-PD Configuration Utility and its associated documentation at the following link:

<http://www.cypress.com/documentation/software-and-drivers/ez-pd-configuration-utility>

**Figure 1. EZ-PD CCG2 Block Diagram**


## Functional Overview

### CPU and Memory Subsystem

#### CPU

The Cortex-M0 CPU in EZ-PD CCG2 is part of the 32-bit MCU subsystem, which is optimized for low-power operation with extensive clock gating. It mostly uses 16-bit instructions and executes a subset of the Thumb-2 instruction set. This enables fully compatible binary upward migration of the code to higher performance processors such as the Cortex-M3 and M4, thus enabling upward compatibility. The Cypress implementation includes a hardware multiplier that provides a 32-bit result in one cycle. It includes a nested vectored interrupt controller (NVIC) block with 32 interrupt inputs and also includes a Wakeup Interrupt Controller (WIC). The WIC can wake the processor up from the Deep Sleep mode, allowing power to be switched off to the main processor when the chip is in the Deep Sleep mode. The Cortex-M0 CPU provides a Non-Maskable Interrupt (NMI) input, which is made available to the user when it is not in use for system functions requested by the user.

The CPU also includes a serial wire debug (SWD) interface, which is a 2-wire form of JTAG. The debug configuration used for EZ-PD CCG2 has four break-point (address) comparators and two watchpoint (data) comparators.

#### Flash

The EZ-PD CCG2 device has a flash module with a flash accelerator, tightly coupled to the CPU to improve average access times from the flash block. The flash block is designed to deliver 1 wait-state (WS) access time at 48 MHz and with 0-WS access time at 24 MHz. The flash accelerator delivers 85% of single-cycle SRAM access performance on average. Part of the flash module can be used to emulate EEPROM operation if required.

#### SROM

A supervisory ROM that contains boot and configuration routines is provided.

## Peripherals

### Serial Communication Blocks (SCB)

EZ-PD CCG2 has two SCBs, which can be configured to implement an I<sup>2</sup>C, SPI, or UART interface. The hardware I<sup>2</sup>C blocks implement full multi-master and slave interfaces capable of multimaster arbitration. In the SPI mode, the SCB blocks can be configured to act as master or slave.

In the I<sup>2</sup>C mode, the SCB blocks are capable of operating at speeds of up to 1 Mbps (Fast Mode Plus) and have flexible buffering options to reduce interrupt overhead and latency for the CPU. These blocks also support I<sup>2</sup>C that creates a mailbox address range in the memory of EZ-PD CCG2 and effectively reduce I<sup>2</sup>C communication to reading from and writing to an array in memory. In addition, the blocks support 8-deep FIFOs for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduce the need for clock stretching caused by the CPU not having read data on time.

The I<sup>2</sup>C peripherals are compatible with the I<sup>2</sup>C Standard-mode, Fast-mode, and Fast-mode Plus devices as defined in the NXP I<sup>2</sup>C-bus specification and user manual ([UM10204](#)). The I<sup>2</sup>C bus I/Os are implemented with GPIO in open-drain modes.

The I<sup>2</sup>C port on SCB 1 block of EZ-PD CCG2 is not completely compliant with the I<sup>2</sup>C spec in the following respects:

- The GPIO cells for SCB 1's I<sup>2</sup>C port are not overvoltage-tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I<sup>2</sup>C system.
- Fast-mode Plus has an I<sub>OL</sub> specification of 20 mA at a V<sub>OL</sub> of 0.4 V. The GPIO cells can sink a maximum of 8-mA I<sub>OL</sub> with a V<sub>OL</sub> maximum of 0.6 V.
- Fast-mode and Fast-mode Plus specify minimum Fall times, which are not met with the GPIO cell; Slow strong mode can help meet this spec depending on the bus load.

### Timer/Counter/PWM Block (TCPWM)

EZ-PD CCG2 has six TCPWM blocks. Each implements a 16-bit timer, counter, pulse-width modulator (PWM), and quadrature decoder functionality. The block can be used to measure the period and pulse width of an input signal (timer), find the number of times a particular event occurs (counter), generate PWM signals, or decode quadrature signals.

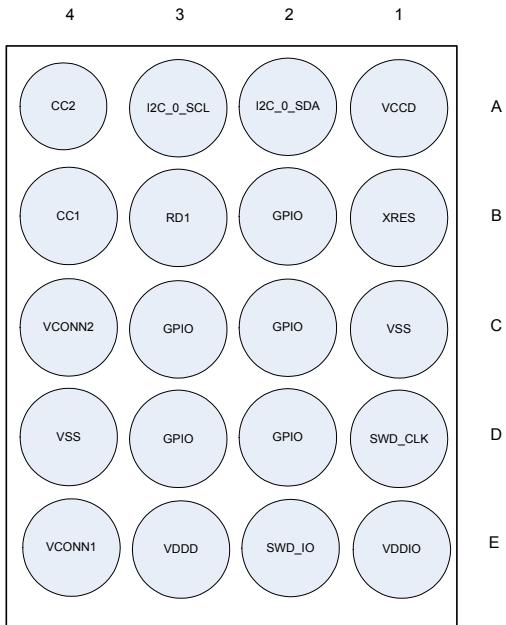
## GPIO

EZ-PD CCG2 has up to 10 GPIOs in addition to the I<sup>2</sup>C and SWD pins, which can also be used as GPIOs. The I<sup>2</sup>C pins from SCB 0 are overvoltage-tolerant. The number of available GPIOs vary with the package. The GPIO block implements the following:

- Seven drive strength modes:
  - Input only
  - Weak pull-up with strong pull-down
  - Strong pull-up with weak pull-down
  - Open drain with strong pull-down
  - Open drain with strong pull-up
  - Strong pull-up with strong pull-down
  - Weak pull-up with weak pull-down
- Input threshold select (CMOS or LVTTL)
- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes
- Hold mode for latching previous state (used for retaining I/O state in Deep Sleep mode)
- Selectable slew rates for dV/dt related noise control to improve EMI

During power-on and reset, the I/O pins are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin.

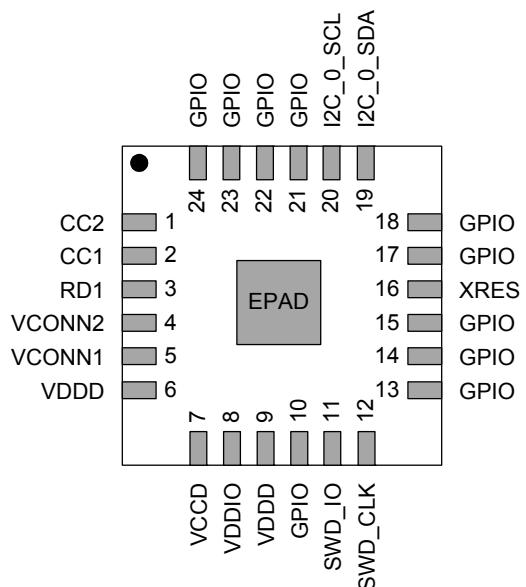
**Figure 3. 20-ball WLCSP EZ-PD CCG2 Ball Map (Bottom (Balls Up) View)**



**Figure 4. 14-pin DFN Pin Map (Top View)**

I2C_0_SCL	1	14	I2C_0_SDA
VSS	2	13	GPIO
CC1	3	12	XRES
VCONN2	4	11	GPIO
VCONN1	5	10	GPIO
VCCD	6	9	SWD_CLK
VDDD	7	8	SWD_IO

**Figure 5. 24-Pin QFN Pin Map (Top View)**

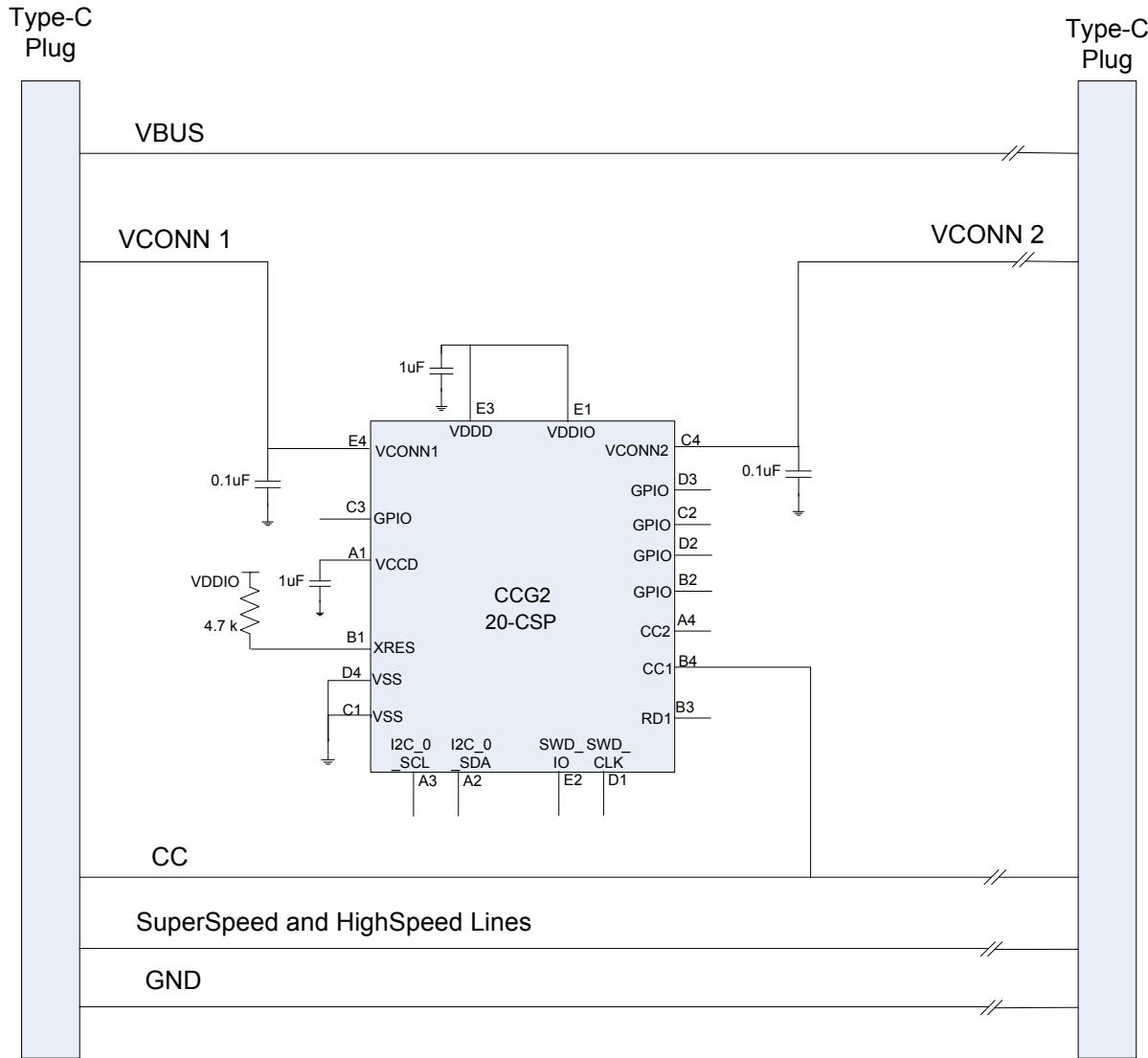


## Application Diagrams

Figure 7 and Figure 8 show the application diagrams of a Passive EMCA application using CCG2 devices. Figure 7 shows the application using a single CCG2 device per cable present at one of the two plugs, whereas Figure 8 shows the same with two CCG2 devices per cable present at each plug. The VBUS signal, the SuperSpeed lines, HighSpeed lines, and CC lines are connected directly from one end to another.

The application diagram shown in Figure 7 requires a single VCONN wire to run through the cable so that the CCG2 device can be powered irrespective of which plug is connected to the host (DFP). However, in the application diagram shown in Figure 8, the VCONN signal does not run through the entire cable, but only runs to the respective VCONN pin of the CCG2 device at each end of the plug. Also, only one CCG2 device is powered at any given instance, depending on which one is nearer to the DFP that supplies VCONN.

**Figure 7. Passive EMCA Application – Single EZ-PD CCG2 Per Cable**



**Figure 8. Passive EMCA Application – Single EZ-PD CCG2 Per Plug**

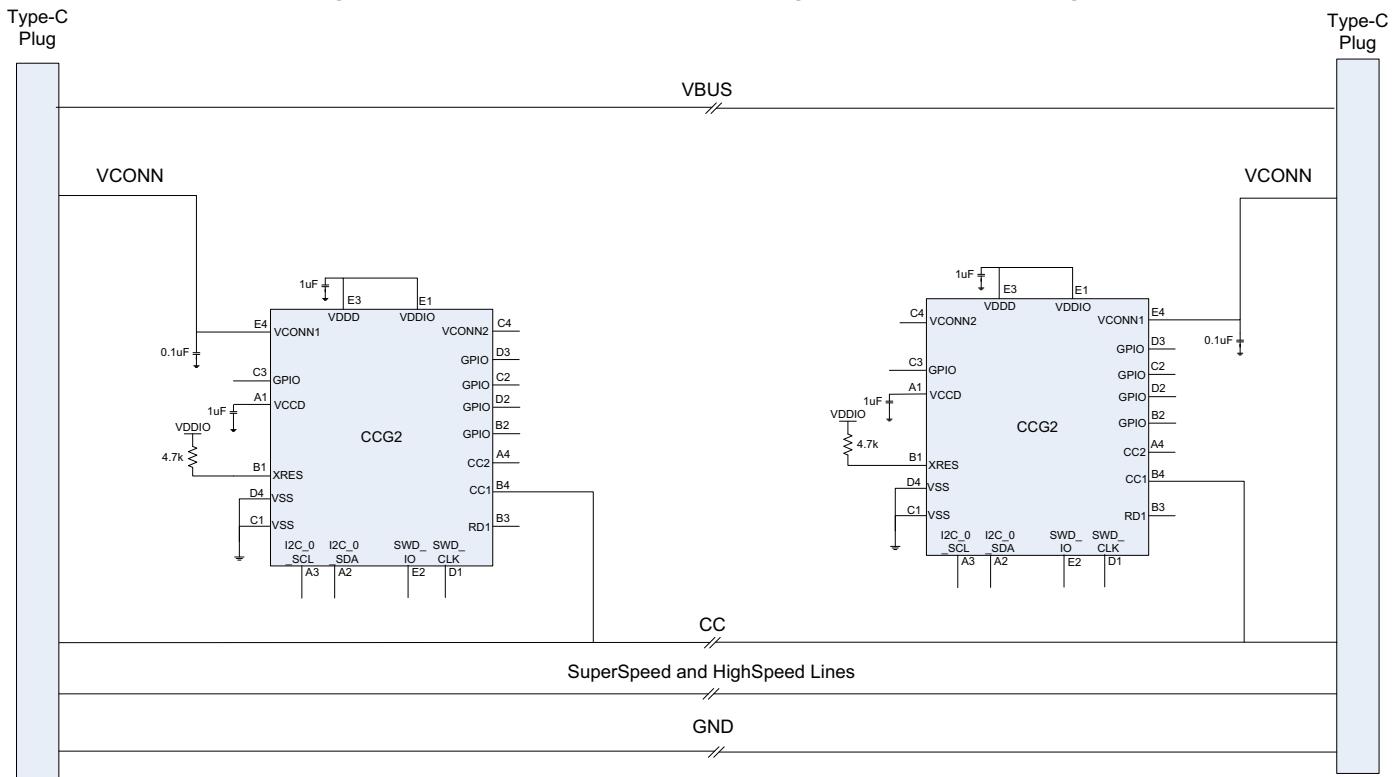


Figure 9 shows a CCG2 device being used in a UFP application (tablet with a Type-C port) only as a power consumer.

The Type-C receptacle brings in HighSpeed and SuperSpeed lines, which are connected directly to the applications processor. The VBUS line from the Type-C receptacle goes directly to the UFP (tablet) charger circuitry. The applications processor communicates over the I<sup>2</sup>C signal with the CCG2 device, and the CC1 and CC2 lines from the Type-C receptacle are connected directly to the respective CC1/2 pins of the CCG2 device.

**Figure 9. Upstream Facing Port (UFP) Application – Tablet with a Type-C Port**

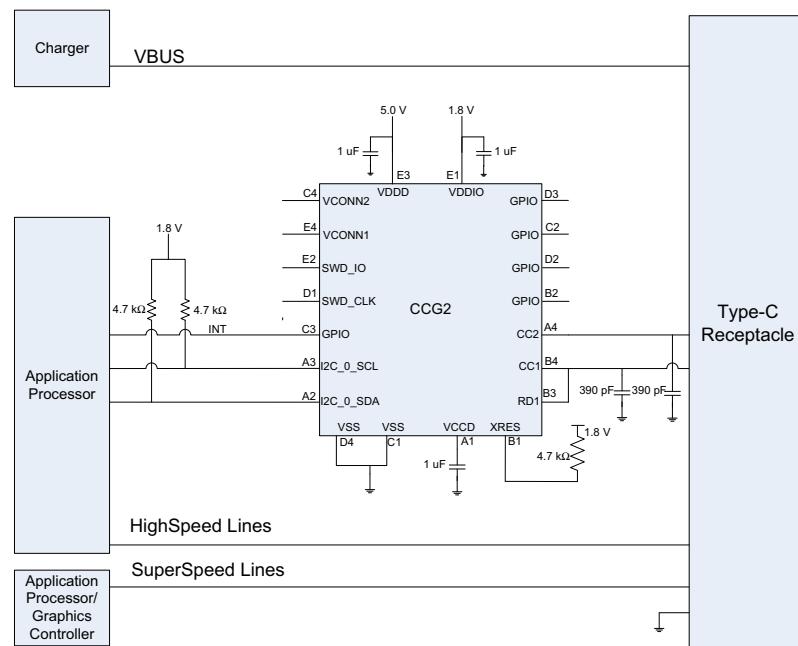


Figure 10 shows a Notebook DRP application diagram using a CCG2 device. The Type-C port can be used as a power provider or a power consumer. The CCG2 device communicates with the Embedded controller (EC) over I<sup>2</sup>C. It also controls the Data Mux to route the High Speed signals either to the USB chipset (during normal mode) or the DisplayPort Chipset (during Alternate Mode). The SBU lines, SuperSpeed and HighSpeed lines are routed directly from the Display Mux of the notebook to the Type-C receptacle.

Optional FETs are provided for applications that need to provide power for accessories and cables using the VCONN pin of the Type-C receptacle. VBUS FETs are also used for providing power over VBUS and for consuming power over VBUS. A VBUS\_DISCHARGE FET controlled by CCG2 device is used to quickly discharge VBUS after the Type-C connection is detached.

**Figure 10. Dual Role Port (DRP) Application**

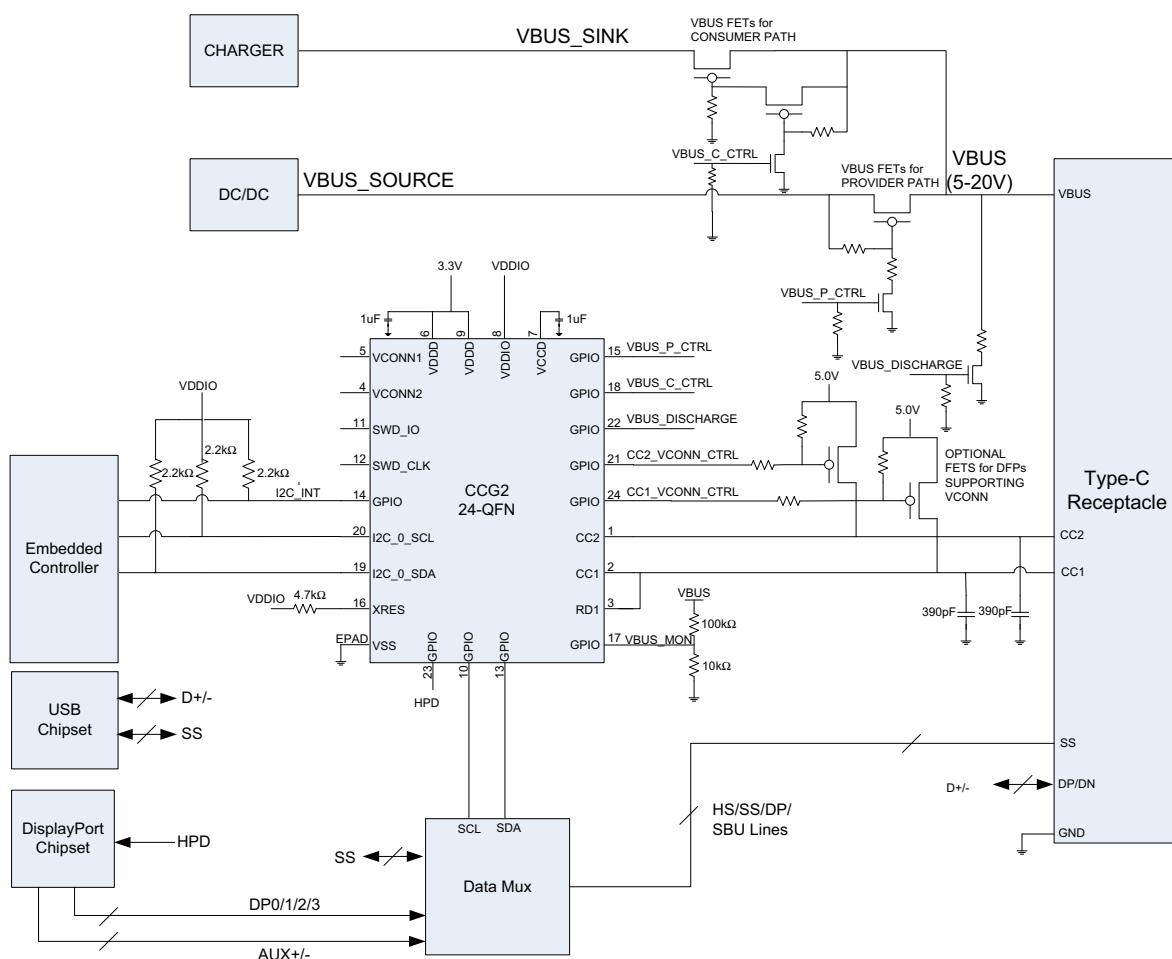


Figure 11 shows a CCG2 receptacle-based Power Adapter application in which the CCG2 device is used as a DFP. CCG2 integrates all termination resistors and uses GPIOs (VSEL\_0 and VSEL\_1) to indicate the negotiated power profile. The VBUS

voltage on the Type-C port is monitored using internal ADC to detect undervoltage and overvoltage conditions on VBUS. To ensure quick discharge of VBUS when the power adapter cable is detached, a discharge path is also provided.

**Figure 11. Downstream Facing Port (DFP) Application**

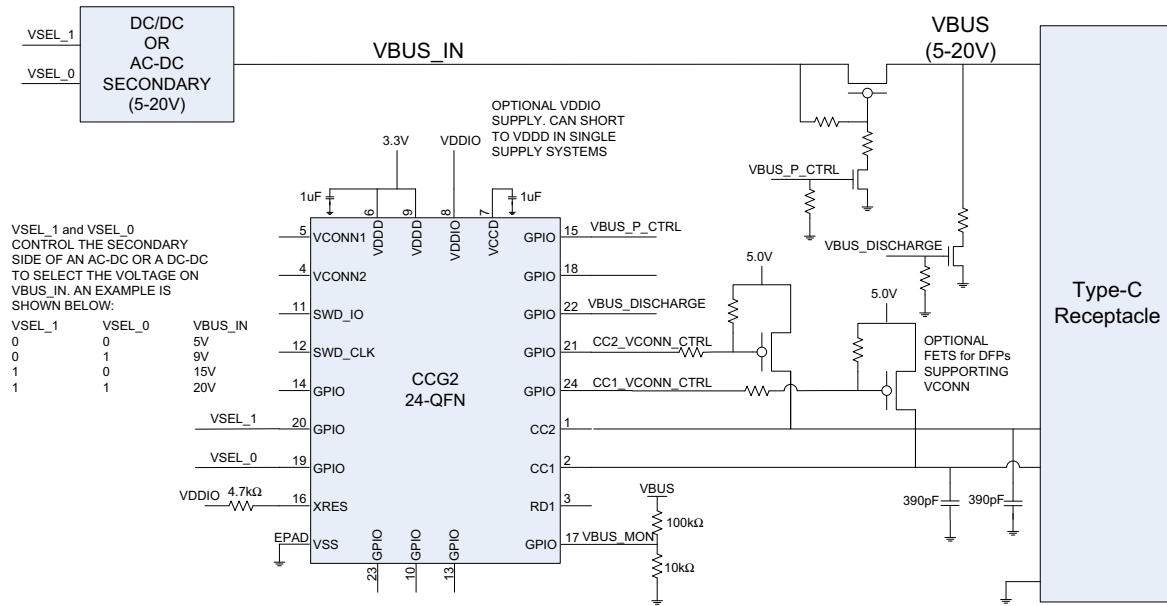


Figure 12 shows a USB Type-C to HDMI/DVI/VGA adapter application, which enables connectivity between a PC that supports a Type-C port with DisplayPort Alternate Mode support and a legacy monitor that has HDMI/DVI/VGA interface. It enables users of any Notebook that implements USB-Type C to connect to other display types.

This application has a Type-C plug on one end and the legacy video (HDMI/DVI/VGA) receptacle on the other end. This appli-

cation meets the requirements described in Section 4.3 of the VESA DisplayPort Alt Mode on USB Type-C Standard Version 1.0. This application supports display output at a resolution of up to 4K Ultra HD (3840x2160) at 60 Hz. It also supports the USB Billboard Device Class, which is required by the USB PD specification for enumeration of any accessories that support Alternate Mode when connected to a host PC.

**Figure 12. USB Type-C to HDMI/DVI/VGA Dongle Application Diagram**

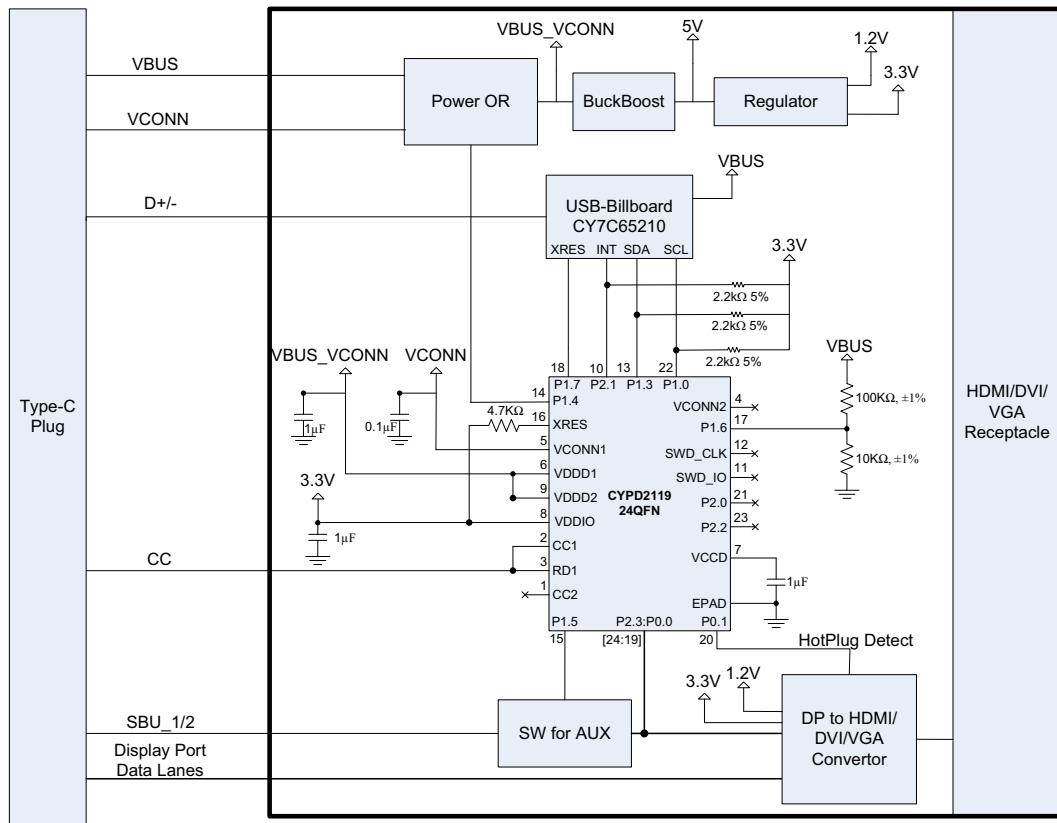


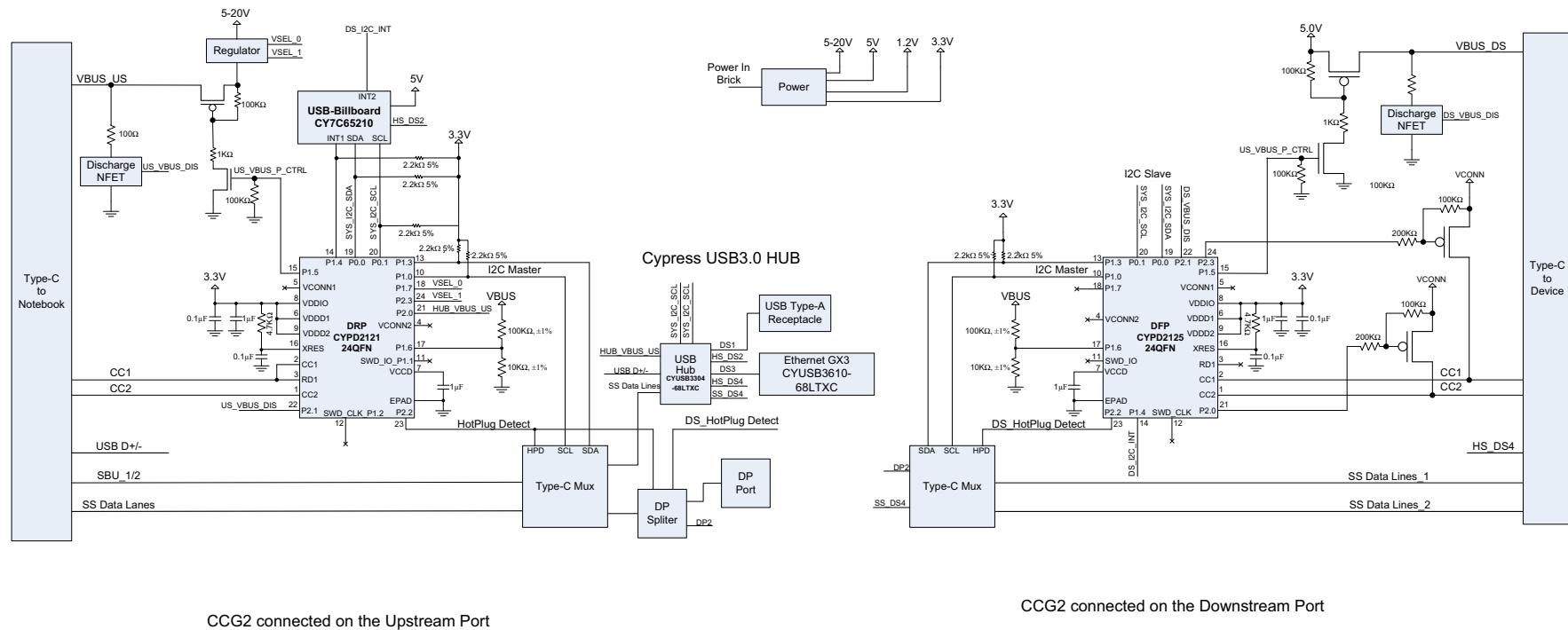
Figure 14 shows a CCG2 Monitor/Dock application diagram. It enables connectivity between a USB Type-C host system on the Upstream port and multiple Display/Data devices on the Downstream port. This application has a USB Type-C receptacle on the Upstream port, which supports data, power, and display. On the Downstream port, this application supports: USB Type-A, Gigabit Ethernet, DisplayPort, and USB Type-C receptacle.

The main features of this solution are:

- Powered from an external 24-V DC power adapter
- Provides up to 45 W (15 V at 3A) on the Upstream Type-C port and up to 15 W (5 V at 3A) on the Downstream USB Type-C port

- Provides simultaneous 4K display output with USB 3.1 Gen 1 on the USB Type-A port
- Four-lane display on the DisplayPort connector
- Multi-Stream support on DisplayPort and Downstream Type-C port
- USB 3.1 Gen 1 hub for USB port expansion
- Gigabit Ethernet using RJ45 connector
- Supports firmware upgrade of CCG2 controllers, HX3 Hub controller, and Billboard controller

**Figure 14. CCG2 in Dock/Monitor Application Diagram**



## Electrical Specifications

### Absolute Maximum Ratings

**Table 1. Absolute Maximum Ratings<sup>[1]</sup>**

Parameter	Description	Min	Typ	Max	Units	Details/Conditions
V <sub>DDD_MAX</sub>	Digital supply relative to V <sub>SS</sub>	-0.5	—	6	V	Absolute max
V <sub>CONN1_MAX</sub>	Max supply voltage relative to V <sub>SS</sub>	—	—	6	V	Absolute max
V <sub>CONN2_MAX</sub>	Max supply voltage relative to V <sub>SS</sub>	—	—	6	V	Absolute max
V <sub>DDIO_MAX</sub>	Max supply voltage relative to V <sub>SS</sub>	—	—	6	V	Absolute max
V <sub>GPIO_ABS</sub>	GPIO voltage	-0.5	—	V <sub>DDIO</sub> + 0.5	V	Absolute max
V <sub>CC_ABS</sub>	Absolute max voltage for CC1 and CC2 pins	—	—	6	V	Absolute max
I <sub>GPIO_ABS</sub>	Maximum current per GPIO	-25	—	25	mA	Absolute max
I <sub>GPIO_injection</sub>	GPIO injection current, Max for V <sub>IH</sub> > V <sub>DDD</sub> , and Min for V <sub>IL</sub> < V <sub>SS</sub>	-0.5	—	0.5	mA	Absolute max, current injected per pin
ESD_HBM	Electrostatic discharge human body model	2200	—	—	V	—
ESD_CDM	Electrostatic discharge charged device model	500	—	—	V	—
LU	Pin current for latch-up	-200	—	200	mA	—
ESD_IEC_CON	Electrostatic discharge IEC61000-4-2	8000	—	—	V	Contact discharge on CC1, CC2, VCONN1, and VCONN2 pins
ESD_IEC_AIR	Electrostatic discharge IEC61000-4-2	15000	—	—	V	Air discharge for pins CC1, CC2, VCONN1, and VCONN2

#### Note

- Usage above the absolute maximum conditions listed in Table 1 may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods of time may affect device reliability. The maximum storage temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature Storage Life. When used below absolute maximum conditions but above normal operating conditions, the device may not operate to specification.

## Device Level Specifications

All specifications are valid for  $-40^{\circ}\text{C} \leq \text{TA} \leq 85^{\circ}\text{C}$  and  $\text{TJ} \leq 100^{\circ}\text{C}$ , except where noted. Specifications are valid for 3.0 V to 5.5 V, except where noted.

**Table 2. DC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.PWR#1	$V_{\text{DDD}}$	Power supply input voltage	2.7	—	5.5	V	UFP Applications
SID.PWR#1_A	$V_{\text{DDD}}$	Power supply input voltage	3.0	—	5.5	V	DFP/DRP Applications
SID.PWR#23	$V_{\text{CONN1}}$	Power supply input voltage	4.0	—	5.5	V	—
SID.PWR#23_A	$V_{\text{CONN2}}$	Power supply input voltage	4.0	—	5.5	V	—
SID.PWR#13	$V_{\text{DDIO}}$	GPIO power supply	1.71	—	5.5	V	—
SID.PWR#24	$V_{\text{CCD}}$	Output voltage (for core logic)	—	1.8	—	V	—
SID.PWR#15	$C_{\text{EFC}}$	External regulator voltage bypass on $V_{\text{CCD}}$	1	1.3	1.6	$\mu\text{F}$	X5R ceramic or better
SID.PWR#16	$C_{\text{EXC}}$	Power supply decoupling capacitor on $V_{\text{DDD}}$	—	1	—	$\mu\text{F}$	X5R ceramic or better
SID.PWR#25		Power Supply Decoupling Capacitor on $V_{\text{CONN1}}$ and $V_{\text{CONN2}}$	—	0.1	—	$\mu\text{F}$	X5R ceramic or better

**Active Mode,  $V_{\text{DDD}} = 2.7$  to  $5.5$  V. Typical values measured at  $V_{\text{DD}} = 3.3$  V.**

SID.PWR#12	$I_{\text{DD12}}$	Supply current	—	7.5	—	mA	$V_{\text{CONN1}} \text{ or } V_{\text{CONN2}} = 5$ V, $T_{\text{A}} = 25^{\circ}\text{C}$ , CC I/O IN Transmit or Receive, $R_{\text{A}}$ disconnected, no I/O sourcing current, CPU at 12 MHz
------------	-------------------	----------------	---	-----	---	----	--

**Sleep Mode,  $V_{\text{DDD}} = 2.7$  to  $5.5$  V**

SID25A	$I_{\text{DD20A}}$	$I^2\text{C}$ wakeup. WDT ON. IMO at 48 MHz	—	2.0	3.0	mA	$V_{\text{DDD}} = 3.3$ V, $T_{\text{A}} = 25^{\circ}\text{C}$ , all blocks except CPU are ON, CC I/O ON, no I/O sourcing current
--------	--------------------	---	---	-----	-----	----	---

**Deep Sleep Mode,  $V_{\text{DDD}} = 2.7$  to  $3.6$  V (Regulator on)**

SID_DS_RA	$I_{\text{DD_DS_RA}}$	$V_{\text{CONN1}} = 5.0$ , $R_{\text{A}}$ termination disabled	—	100	—	$\mu\text{A}$	$V_{\text{CONN1}}, V_{\text{CONN2}} = 5$ V, $T_{\text{A}} = 25^{\circ}\text{C}$ . $R_{\text{A}}$ termination disabled on $V_{\text{CONN1}}$ and $V_{\text{CONN2}}$ , see SID.PD.7. VCONN leaker circuits turned off during deep sleep
SID34	$I_{\text{DD29}}$	$V_{\text{DDD}} = 2.7$ to $3.6$ V. $I^2\text{C}$ wakeup and WDT ON	—	50	—	$\mu\text{A}$	$R_{\text{A}}$ switch disabled on $V_{\text{CONN1}}$ and $V_{\text{CONN2}}$ . $V_{\text{DDD}} = 3.3$ V, $T_{\text{A}} = 25^{\circ}\text{C}$
SID_DS	$I_{\text{DD_DS}}$	$V_{\text{DDD}} = 2.7$ to $3.6$ V. CC wakeup ON	—	2.5	—	$\mu\text{A}$	Power source = $V_{\text{DDD}}$ , Type-C not attached, CC enabled for wakeup, $R_{\text{P}}$ disabled

**XRES Current**

SID307	$I_{\text{DD_XR}}$	Supply current while XRES asserted	—	1	10	$\mu\text{A}$	—
--------	--------------------	------------------------------------	---	---	----	---------------	---

**Table 5. I/O AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID70	T <sub>RISEF</sub>	Rise time	2	—	12	ns	3.3-V V <sub>DDIO</sub> , Cload = 25 pF
SID71	T <sub>FALLF</sub>	Fall time	2	—	12	ns	3.3-V V <sub>DDIO</sub> , Cload = 25 pF

**XRES**
**Table 6. XRES DC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.XRES#1	V <sub>IH</sub>	Input voltage HIGH threshold	0.7 × V <sub>DDIO</sub>	—	—	V	CMOS input
SID.XRES#2	V <sub>IL</sub>	Input voltage LOW threshold	—	—	0.3 × V <sub>DDIO</sub>	V	CMOS input
SID.XRES#3	C <sub>IN</sub>	Input capacitance	—	—	7	pF	Guaranteed by characterization
SID.XRES#4	V <sub>HYSXRES</sub>	Input voltage hysteresis	—	—	0.05 × V <sub>DDIO</sub>	mV	Guaranteed by characterization

## Digital Peripherals

The following specifications apply to the Timer/Counter/PWM peripherals in the Timer mode.

### Pulse Width Modulation (PWM) for GPIO Pins

**Table 7. PWM AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.TCPWM.3	T <sub>CPWMFREQ</sub>	Operating frequency	—	F <sub>c</sub>	—	MHz	F <sub>c</sub> max = CLK_SYS. Maximum = 48 MHz.
SID.TCPWM.4	T <sub>PWMENEXT</sub>	Input trigger pulse width	—	2/F <sub>c</sub>	—	ns	For all Trigger Events
SID.TCPWM.5	T <sub>PWMEXT</sub>	Output trigger pulse width	—	2/F <sub>c</sub>	—	ns	Minimum possible width of Overflow, Underflow, and CC (Counter equals Compare value) outputs
SID.TCPWM.5A	T <sub>CRES</sub>	Resolution of counter	—	1/F <sub>c</sub>	—	ns	Minimum time between successive counts
SID.TCPWM.5B	PWM <sub>RES</sub>	PWM resolution	—	1/F <sub>c</sub>	—	ns	Minimum pulse width of PWM output
SID.TCPWM.5C	Q <sub>RES</sub>	Quadrature inputs resolution	—	1/F <sub>c</sub>	—	ns	Minimum pulse width between quadrature-phase inputs

$I^2C$ 
**Table 8. Fixed I<sup>2</sup>C DC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID149	$I_{I^2C1}$	Block current consumption at 100 kbps	—	—	60	$\mu A$	—
SID150	$I_{I^2C2}$	Block current consumption at 400 kbps	—	—	185	$\mu A$	—
SID151	$I_{I^2C3}$	Block current consumption at 1 Mbps	—	—	390	$\mu A$	—
SID152	$I_{I^2C4}$	$I^2C$ enabled in Deep Sleep mode	—	—	1.4	$\mu A$	—

**Table 9. Fixed I<sup>2</sup>C AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID153	$F_{I^2C1}$	Bit rate	—	—	1	Mbps	—

**Table 10. Fixed UART DC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID160	$I_{UART1}$	Block current consumption at 100 Kbps	—	—	125	$\mu A$	Guaranteed by characterization
SID161	$I_{UART2}$	Block current consumption at 1000 Kbps	—	—	312	$\mu A$	Guaranteed by characterization

**Table 11. Fixed UART AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID162	$F_{UART}$	Bit rate	—	—	1	Mbps	Guaranteed by characterization

**Table 12. Fixed SPI DC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID163	$I_{SPI1}$	Block current consumption at 1 Mbps	—	—	360	$\mu A$	Guaranteed by characterization
SID164	$I_{SPI2}$	Block current consumption at 4 Mbps	—	—	560	$\mu A$	Guaranteed by characterization
SID165	$I_{SPI3}$	Block current consumption at 8 Mbps	—	—	600	$\mu A$	Guaranteed by characterization

**Table 13. Fixed SPI AC Specifications**

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID166	$F_{SPI}$	SPI Operating frequency (Master; 6X oversampling)	—	—	8	MHz	Guaranteed by characterization

**Internal Low-Speed Oscillator**
**Table 22. ILO DC Specifications**

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID231	$I_{ILO}$	ILO operating current at 32 kHz	–	0.3	1.05	µA	Guaranteed by Characterization
SID233	$I_{ILOLEAK}$	ILO leakage current	–	2	15	nA	Guaranteed by Design

**Table 23. ILO AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID234	$T_{STARTILO}$	ILO startup time	–	–	2	ms	Guaranteed by characterization
SID236	$T_{ILODUTY}$	ILO duty cycle	40	50	60	%	Guaranteed by characterization
SID.CLK#5	$F_{ILO}$	ILO Frequency	20	40	80	kHz	–

**Power Down**
**Table 24. PD DC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.PD.1	$R_{P\_std}$	DFP CC termination for default USB Power	64	80	96	µA	–
SID.PD.2	$R_{P\_1.5A}$	DFP CC termination for 1.5A power	166	180	194	µA	–
SID.PD.3	$R_{P\_3.0A}$	DFP CC termination for 3.0A power	304	330	356	µA	–
SID.PD.4	$R_d$	UFP CC termination	4.59	5.1	5.61	kΩ	–
SID.PD.5	$R_{d\_DB}$	UFP Dead Battery CC termination on RD1 and CC2	4.08	5.1	6.12	kΩ	All supplies forced to 0 V and 0.6 V applied at RD1 or CC2
SID.PD.6	$R_A$	Power cable termination	0.8	1.0	1.2	kΩ	All supplies forced to 0 V and 0.2 V applied at $V_{CONN1}$ or $V_{CONN2}$
SID.PD.7	$R_{a\_OFF}$	Power cable termination - Disabled	0.4	0.75	–	MΩ	2.7 V applied at $V_{CONN1}$ or $V_{CONN2}$ with $R_A$ disabled
SID.PD.8	$R_{leak\_1}$	$V_{CONN}$ leaker for 0.1-µF load	–	–	216	kΩ	Managed Active Cable (MAC) discharge
SID.PD.9	$R_{leak\_2}$	$V_{CONN}$ leaker for 0.5-µF load	–	–	41.2	kΩ	
SID.PD.10	$R_{leak\_3}$	$V_{CONN}$ leaker for 1.0-µF load	–	–	19.6	kΩ	
SID.PD.11	$R_{leak\_4}$	$V_{CONN}$ leaker for 2.0-µF load	–	–	9.8	kΩ	
SID.PD.12	$R_{leak\_5}$	$V_{CONN}$ leaker for 5.0-µF load	–	–	4.1	kΩ	
SID.PD.13	$R_{leak\_6}$	$V_{CONN}$ leaker for 10-µF load	–	–	2.0	kΩ	
SID.PD.14	$I_{leak}$	Leaker on $V_{CONN1}$ and $V_{CONN2}$ for discharge upon cable detach	150	–	–	µA	–

Analog-to-Digital Converter

**Table 25. ADC DC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.ADC.1	Resolution	ADC resolution	–	8	–	bits	Guaranteed by characterization
SID.ADC.2	INL	Integral non-linearity	–1.5	–	1.5	LSB	Guaranteed by characterization
SID.ADC.3	DNL	Differential non-linearity	–2.5	–	2.5	LSB	Guaranteed by characterization
SID.ADC.4	Gain Error	Gain error	–1	–	1	LSB	Guaranteed by characterization

**Table 26. ADC AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.ADC.5	SLEW_Max	Rate of change of sampled voltage signal	–	–	3	V/ms	Guaranteed by characterization

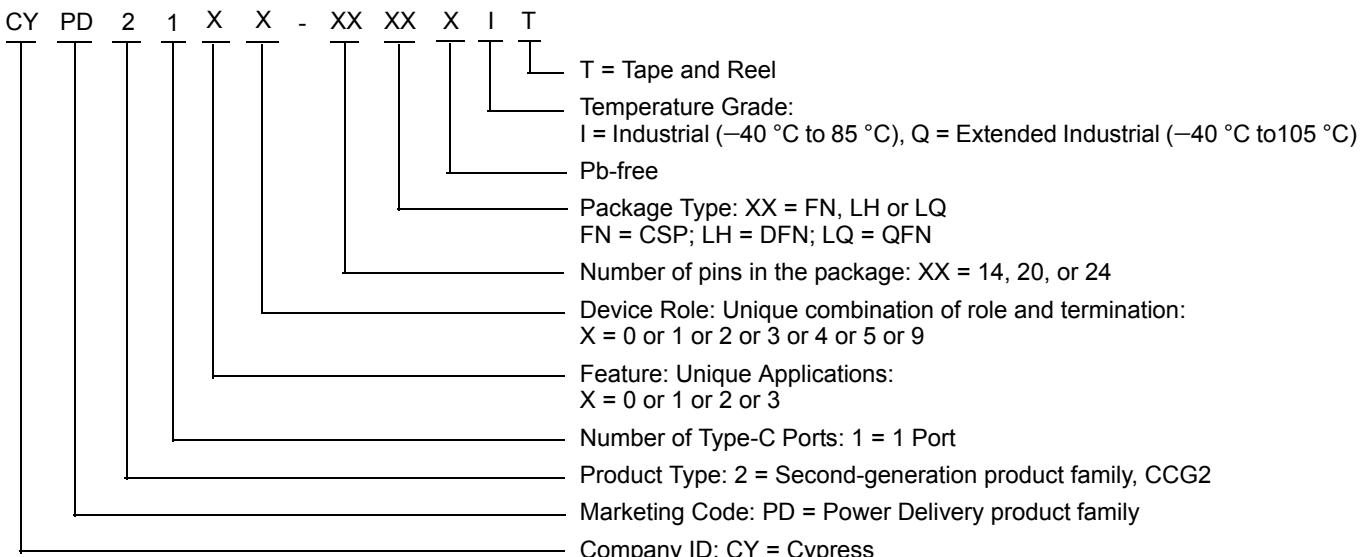
## Ordering Information

The EZ-PD CCG2 part numbers and features are listed in [Table 27](#).

**Table 27. EZ-PD CCG2 Ordering Information**

Part Number	Application	Type-C Ports	Termination Resistor	Role	Package
CYPD2103-20FNXIT	Cable	1	R <sub>A</sub> <sup>[4]</sup>	Cable	20-ball CSP
CYPD2103-14LHXIT	Cable	1	R <sub>A</sub> <sup>[4]</sup>	Cable	14-pin DFN
CYPD2104-20FNXIT	Accessory	1	R <sub>D</sub> <sup>[5]</sup>	Accessory	20-ball CSP
CYPD2105-20FNXIT	Active Cable	1	R <sub>A</sub> <sup>[4]</sup>	Active Cable	20-ball CSP
CYPD2119-24LQXIT	C-DP	1	R <sub>D</sub> <sup>[5]</sup>	UFP	24-pin QFN
CYPD2120-24LQXIT	C-HDMI	1	R <sub>D</sub> <sup>[5]</sup>	UFP	24-pin QFN
CYPD2121-24LQXIT	Dock/Monitor Upstream port	1	R <sub>P</sub> <sup>[6]</sup> , R <sub>D</sub> <sup>[5]</sup>	DRP	24-pin QFN
CYPD2122-20FNXIT	Tablet	1	R <sub>P</sub> <sup>[6]</sup> , R <sub>D</sub> <sup>[5]</sup>	DRP	20-ball CSP
CYPD2122-24LQXI	Notebook	1	R <sub>P</sub> <sup>[6]</sup> , R <sub>D</sub> <sup>[5]</sup>	DRP	24-pin QFN
CYPD2122-24LQXIT	Notebook	1	R <sub>P</sub> <sup>[6]</sup> , R <sub>D</sub> <sup>[5]</sup>	DRP	24-pin QFN
CYPD2125-24LQXIT	Dock/Monitor Downstream port	1	R <sub>P</sub> <sup>[6]</sup>	DFP	24-pin QFN
CYPD2134-24LQXIT	DFP	1	R <sub>P</sub> <sup>[6]</sup>	DFP	24-pin QFN
CYPD2134-24LQXQT	DFP	1	R <sub>P</sub> <sup>[6]</sup>	DFP	24-pin QFN

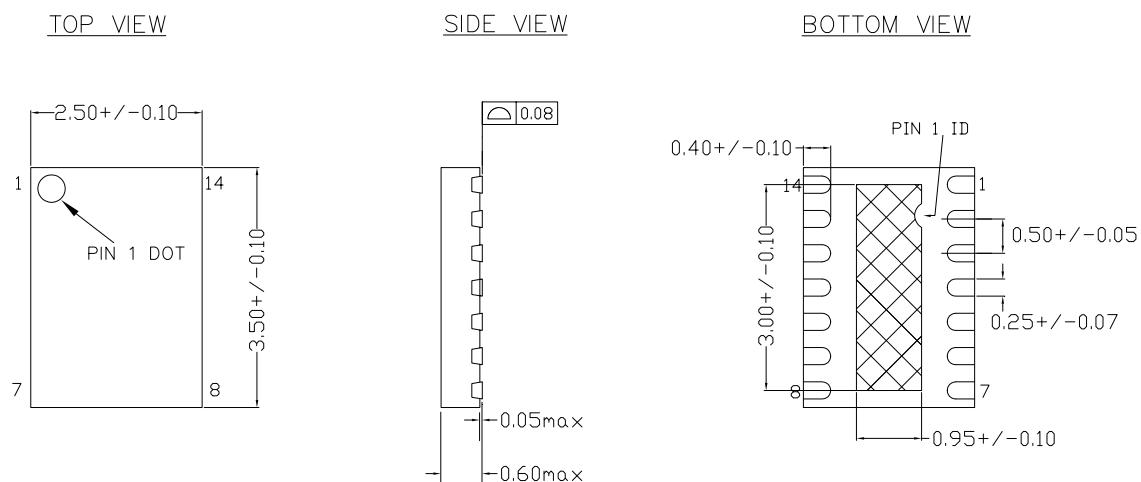
## Ordering Code Definitions



### Notes

4. Termination resistor denoting an EMCA.
5. Termination resistor denoting an accessory or upstream facing port.
6. Termination resistor denoting a downstream facing port.

**Figure 16. 14-pin DFN (2.5 × 3.5 × 0.6 mm), LH14A, 0.95 × 3.00 E-Pad (Sawn) Package Outline, 001-96312**

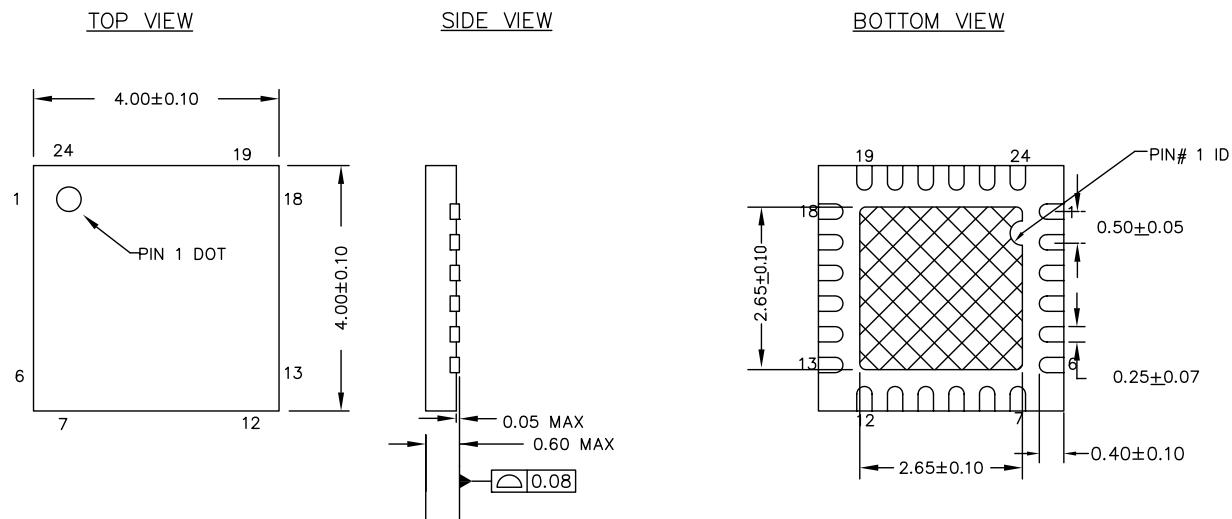


NOTES :

1. HATCH AREA IS SOLDERABLE EXPOSED METAL
2. ALL DIMENSIONS ARE IN MILLIMETERS

001-96312 \*\*

**Figure 17. 24-Pin QFN (4 × 4 × 0.55 mm), LQ24A, 2.65 × 2.65 E-Pad (Sawn) Package Outline, 001-13937**



NOTES :

1. HATCH IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC # MO-248
3. PACKAGE WEIGHT : 29 ± 3 mg
4. ALL DIMENSIONS ARE IN MILLIMETERS

001-13937 \*F

## References and Links To Applications Collaterals

### Knowledge Base Articles

- Key Differences Among EZ-PD™ CCG1, CCG2, CCG3 and CCG4 - KBA210740
  - Programming EZ-PD™ CCG2, EZ-PD™ CCG3 and EZ-PD™ CCG4 Using PSoC® Programmer and MiniProg3 - KBA96477
  - CCGx Frequently Asked Questions (FAQs) - KBA97244
  - Handling Precautions for CY4501 CCG1 DVK - KBA210560
  - Cypress EZ-PD™ CCGx Hardware - KBA204102
  - Difference between USB Type-C and USB-PD - KBA204033
  - CCGx Programming Methods - KBA97271
  - Getting started with Cypress USB Type-C Products - KBA04071
  - Type-C to DisplayPort Cable Electrical Requirements
  - Dead Battery Charging Implementation in USB Type-C Solutions - KBA97273
  - Termination Resistors Required for the USB Type-C Connector – KBA97180
  - VBUS Bypass Capacitor Recommendation for Type-C Cable and Type-C to Legacy Cable/Adapter Assemblies – KBA97270
  - Need for Regulator and Auxiliary Switch in Type-C to DisplayPort (DP) Cable Solution - KBA97274
  - Need for a USB Billboard Device in Type-C Solutions – KBA97146
  - CCG1 Devices in Type-C to Legacy Cable/Adapter Assemblies – KBA97145
  - Cypress USB Type-C Controller Supported Solutions – KBA97179
  - Termination Resistors for Type-C to Legacy Ports – KBA97272
  - Handling Instructions for CY4502 CCG2 Development Kit – KBA97916
  - Thunderbolt™ Cable Application Using CCG3 Devices - KBA210976
  - Power Adapter Application Using CCG3 Devices - KBA210975
  - Methods to Upgrade Firmware on CCG3 Devices - KBA210974
  - Device Flash Memory Size and Advantages - KBA210973
  - Applications of EZ-PD™ CCG4 - KBA210739
- Application Notes*
- AN96527 - Designing USB Type-C Products Using Cypress's CCG1 Controllers

- AN95615 - Designing USB 3.1 Type-C Cables Using EZ-PD™ CCG2

- AN95599 - Hardware Design Guidelines for EZ-PD™ CCG2
- AN210403 - Hardware Design Guidelines for Dual Role Port Applications Using EZ-PD™ USB Type-C Controllers
- AN210771 - Getting Started with EZ-PD™ CCG4

### Reference Designs

- EZ-PD™ CCG2 Electronically Marked Cable Assembly (EMCA) Paddle Card Reference Design
- EZ-PD™ CCG2 USB Type-C to DisplayPort Cable Solution
- CCG1 USB Type-C to DisplayPort Cable Solution
- CCG1 USB Type-C to HDMI/DVI/VGA Adapter Solution
- EZ-PD™ CCG2 USB Type-C to HDMI Adapter Solution
- CCG1 Electronically Marked Cable Assembly (EMCA) Paddle Card Reference Design
- CCG1 USB Type-C to Legacy USB Device Cable Paddle Card Reference Schematics
- EZ-USB GX3 USB Type-C to Gigabit Ethernet Dongle
- EZ-PD™ CCG2 USB Type-C Monitor/Dock Solution
- CCG2 20W Power Adapter Reference Design
- CCG2 18W Power Adapter Reference Design
- EZ-USB GX3 USB Type-A to Gigabit Ethernet Reference Design Kit

### Kits

- CY4501 CCG1 Development Kit
- CY4502 EZ-PD™ CCG2 Development Kit
- CY4531 EZ-PD CCG3 Evaluation Kit
- CY4541 EZ-PD™ CCG4 Evaluation Kit

### Datasheets

- CCG1 Datasheet: USB Type-C Port Controller with Power Delivery
- CYPD1120 Datasheet: USB Power Delivery Alternate Mode Controller on Type-C
- CCG3: USB Type-C Controller Datasheet
- CCG4: Two-Port USB Type-C Controller Datasheet

## Document History Page

**Description Title:** EZ-PD™ CCG2 Datasheet USB Type-C Port Controller

**Document Number:** 001-93912

Revision	ECN	Orig. of Change	Submission Date	Description of Change
*E	4680071	GAYA	03/07/2015	Release to web
*F	4718374	AKN	04/09/2015	Added 24-pin QFN pin and package information. Added DRP and DFP Application diagrams
*G	4774142	AKN	06/15/2015	Changed datasheet status from Preliminary to Final. Updated Logic Block Diagram. Changed number of GPIOs to 10 and added a note about the number of GPIOs varying depending on the package. Updated Power and Digital Peripherals section. Updated Application diagrams. Added SID.PWR#1_A parameter. Added CYPD2122-20FNXIT part in Ordering Information. Removed Errata.
*H	4979175	VGT	10/23/2015	Updated Figure 1 and Figure 5. Added VCC_ABS spec and updated the SID.ADC.4 parameter. Added "Guaranteed by characterization" note for the following specs: SID.GIO#16, SID.GIO#17, SID.XRES#3, SID 160 to SID 172A, SID 2226, SID 229, SID.ADC.1 to SID.ADC.5.
*I	5028128	VGT	12/04/2015	Updated <a href="#">Application Diagrams</a> : Added <a href="#">Figure 12</a> . Added <a href="#">Figure 13</a> . Added <a href="#">Figure 14</a> . Updated <a href="#">Ordering Information</a> . Added part numbers CYPD2119-24LQXIT, CYPD2120-24LQXIT, CYPD2121-24LQXIT, CYPD2125-24LQXIT.
*J	5186972	VGT	03/28/2016	Updated temperature ranges in <a href="#">Features</a> . Updated <a href="#">Table 28</a> . Updated <a href="#">Ordering Information</a> .
*K	5303957	VGT	06/13/2016	Added <a href="#">Available Firmware and Software Tools</a> . Updated <a href="#">Figure 8</a> : Per the USB PD3.0 spec, SOP" implementation is no longer valid for passive cables. Updated <a href="#">Figure 9</a> , <a href="#">Figure 10</a> , and <a href="#">Figure 11</a> . Added descriptive notes for the application diagrams. Added <a href="#">References and Links To Applications Collaterals</a> . Updated <a href="#">Ordering Information</a> . Updated Cypress logo and copyright information.
*L	5387677	VGT	08/02/2016	Added CYPD2122-24LQXI part number in <a href="#">Ordering Information</a> .